

IN THE SPECIFICATION:

Please amend the specification as follows:

Please substitute the following paragraph for the paragraph at page 5, lns. 2-8:

Now, a description will be given in more detail of preferred embodiments of the present invention with reference to Figs. 1A to 1C. Fig. 1A is a top view showing a pixel portion of a light emitting apparatus in accordance with the present invention. Fig. 1B is a cross-sectional view taken along lines ~~A-A', A'-A" and A"-A'''~~ A-A'-A"-A''' in Fig. 1A, and Fig. 1C is a cross-sectional view taken along lines ~~B-B' and B'-B''~~ B-B'-B'' in Fig. 1A. The light emitting apparatus shown in those figures is in a state before light emitting elements are sealed in the apparatus.

Please substitute the following paragraph for the paragraph at page 9, lns. 2-8:

In a region surrounding (in the exterior of) the pixel portion 202, an IC where a drive circuit that transmits the respective signals to the pixel portion 202 is formed is mounting through a Chip On Glass (herein after: COG) ~~COG~~ system. This embodiment is characterized in that the IC is directed to a drive circuit formed of TFTs on a glass substrate, a quartz substrate or a plastic substrate. In the present specification, the IC having the above features is called "stick driver". It is needless to say that an IC chip where a drive circuit is formed on a silicon substrate through a known IC technique can be used.